

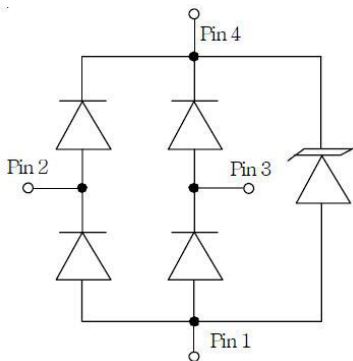
#### Description

The SR70 is a low capacitance TVS diode array, utilizing leading monolithic silicon technology to provide fast response time and low ESD clamping voltage, making this device an ideal solution for protecting voltage sensitive high-speed data lines. The SR70 has a very low capacitance with a typical value at 3pF, and complies with the IEC 61000-4-2 (ESD) with  $\pm 30\text{kV}$  air and  $\pm 30\text{kV}$  contact discharge. It is assembled into a 4-pin SOT-143 lead-free package. The small size, very low capacitance and high ESD surge protection make SR70 an ideal choice to protect cell phone, digital video interfaces, high speed data ports, and many other portable applications. .

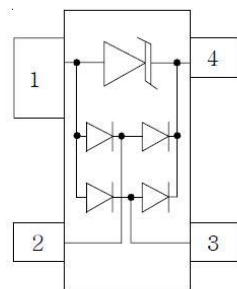
#### Features

- Ultra low capacitance: 3pF typical
- Working voltage: 70V
- Low clamping voltage
- Protects two data lines and one power line
- Complies with following standards:
  - IEC 61000-4-2 (ESD) immunity test
    - Air discharge:  $\pm 30\text{kV}$
    - Contact discharge:  $\pm 30\text{kV}$
  - IEC61000-4-4 (EFT) 40A (5/50ns)
  - IEC61000-4-5 (Lightning) 25A (8/20 $\mu\text{s}$ )
- RoHS Compliant

#### Dimensions & Symbol (Unit: mm Max)



Circuit Diagram



Pin Schematic

#### Mechanical Characteristics

- Package: SOT-143
- Lead Finish: Matte Tin
- Case Material: "Green" Molding Compound.
- UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 3 per J-STD-020
- Terminal Connections: See Diagram Below
- Marking Information: See Below

#### Applications

- Cellular Handsets and Accessories
- Display Ports
- MDDI Ports
- USB Ports
- Digital Visual Interface (DVI)
- PCI Express and Serial SATA Ports

#### Marking Information



#### Ordering information

Part Number	Packaging	Reel Size
SR70	3000/Tape & Reel	7 inch

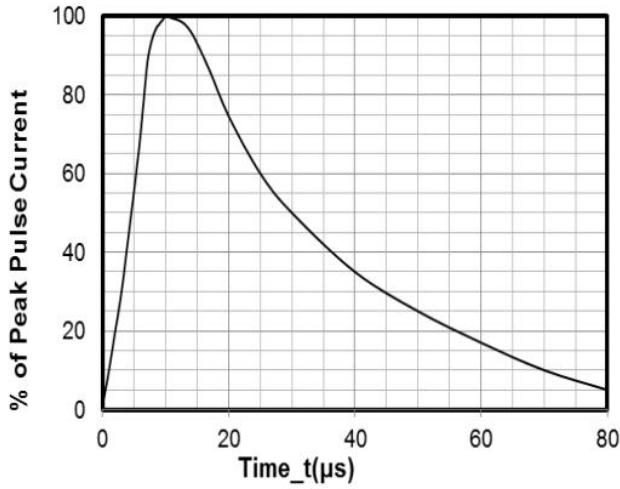
Absolute maximum ratings ( $T_A=25^{\circ}\text{C}$ , RH=45%-75%, unless otherwise noted)

Parameter	Symbol	Value	Unit
Peak Pulse Power (tp=8/20μs waveform)	$P_{ppp}$	70	W
Peak Pulse Current (8/20μs)	$I_{pp}$	25	A
ESD per IEC 61000-4-2 (Air)	$V_{ESD}$	±30	kV
ESD per IEC 61000-4-2 (Contact)		±30	
Operating Temperature Range	$T_J$	-55 to +125	$^{\circ}\text{C}$
Storage Temperature Range	$T_{stg}$	-55 to +150	$^{\circ}\text{C}$

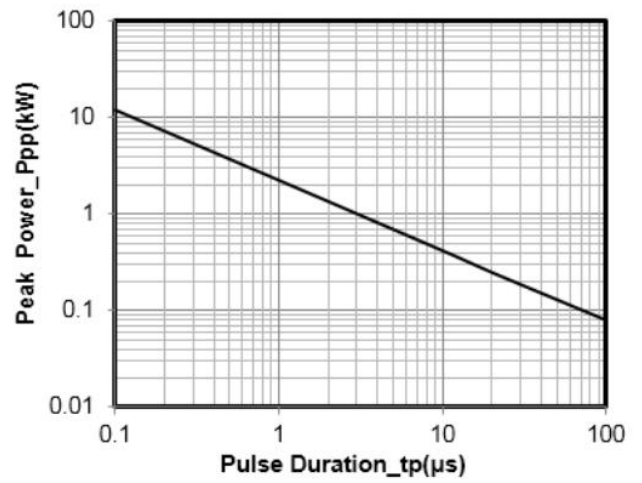
Electrical characteristics ( $T_A=25^{\circ}\text{C}$ )

Parameter	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Working Voltage	$V_{RWM}$			70	V	
Breakdown Voltage	$V_{BR}$	85			V	$I_T = 1\text{mA}$
Reverse Leakage Current	$I_R$			5	μA	$V_{RWM} = 70\text{V}$
Forward Clamping Voltage	$V_C$		1.5		V	$I_{PP} = 1\text{A}$ (8 x 20μs pulse)
Forward Clamping Voltage	$V_C$		5		V	$I_{PP} = 10\text{A}$ (8 x 20μs pulse)
Forward Clamping Voltage	$V_C$		10		V	$I_{PP} = 25\text{A}$ (8 x 20μs pulse)
Junction Capacitance	$C_J$		5	10	pF	$V_R = 0\text{V}$ , $f = 1\text{MHz}$ , any I/O pin to ground
Junction Capacitance	$C_J$		3		pF	$V_R = 0\text{V}$ , $f = 1\text{MHz}$ , between I/O pins

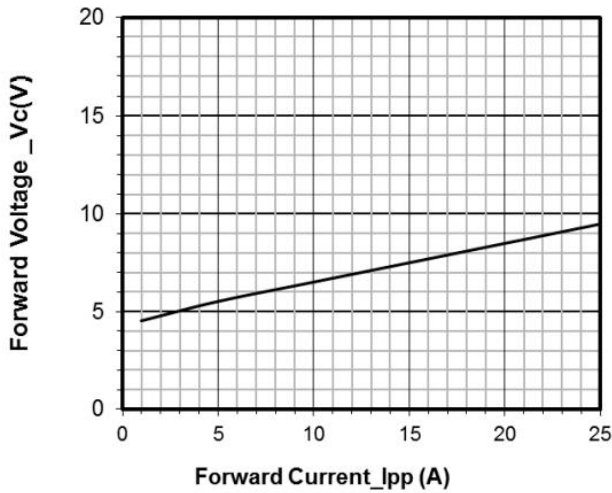
Typical Performance Characteristics ( $T_A=25^{\circ}\text{C}$  unless otherwise Specified)



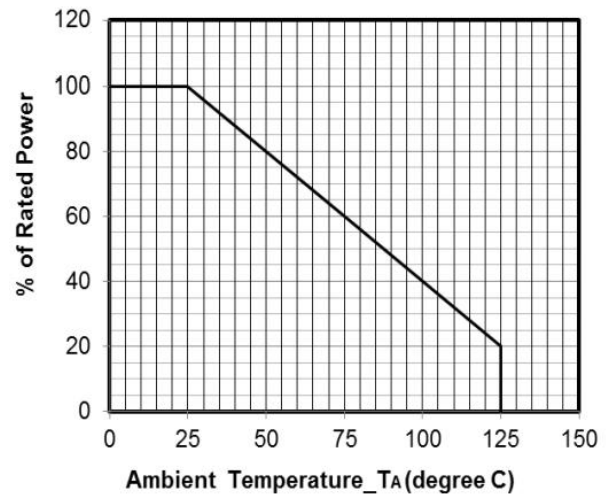
8 X 20µs Pulse Waveform



Peak Pulse Power vs. Pulse Time



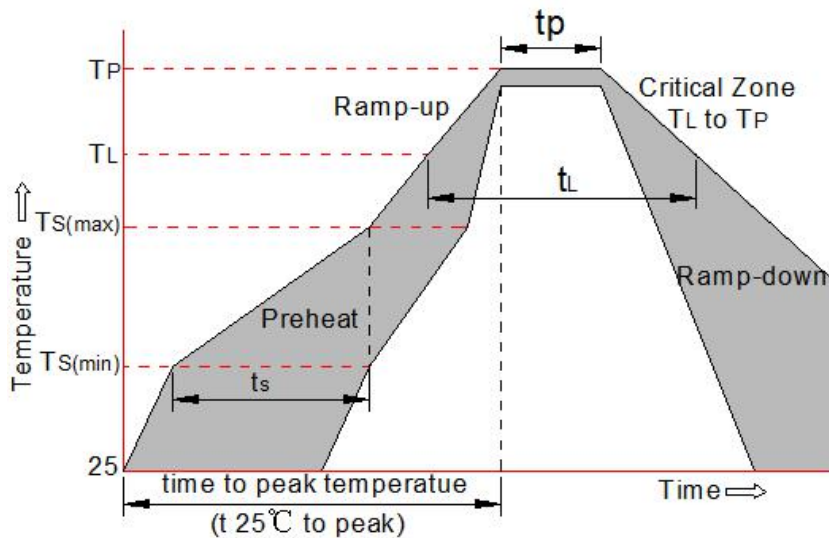
Clamping Voltage vs. Peak Pulse Current



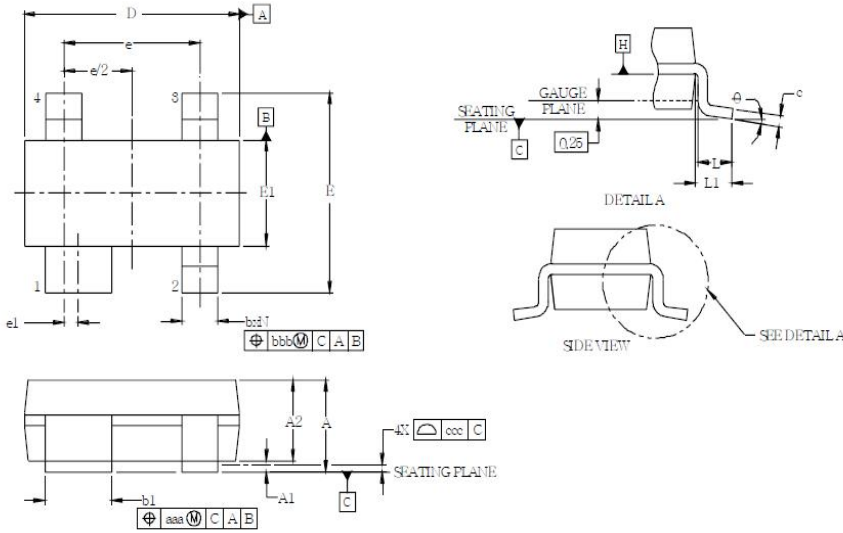
Power Derating Curve

## Soldering Parameters

Reflow Condition		Pb-Free assembly (see as bellow)
Pre Heat	-Temperature Min ( $T_{s(min)}$ )	+150°C
	-Temperature Max( $T_{s(max)}$ )	+200°C
	-Time (Min to Max) ( $t_s$ )	60-180 secs.
Average ramp up rate (Liquid us Temp ( $T_L$ ) to peak)		3°C/sec. Max
$T_{s(max)}$ to $T_L$ - Ramp-up Rate		3°C/sec. Max
Reflow	-Temperature( $T_L$ ) (Liquid us)	+217°C
	-Temperature( $t_L$ )	60-150 secs.
Peak Temp ( $T_p$ )		+260(+0/-5)°C
Time within 5°C of actual Peak Temp ( $t_p$ )		30 secs. Max
Ramp-down Rate		6°C/sec. Max
Time 25°C to Peak Temp ( $T_p$ )		8 min. Max
Do not exceed		+260°C

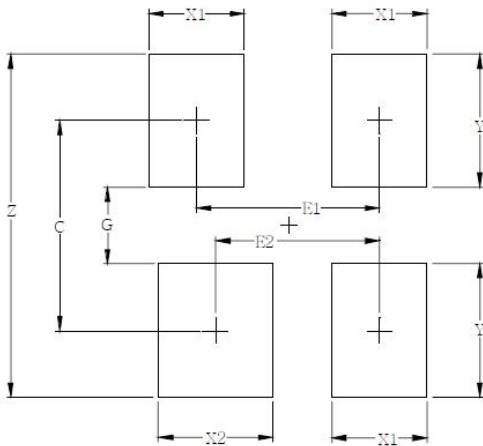


### Package Mechanical Data



SYM	DIMENSIONS		
	MILLIMETERS		
	MIN	NOM	MAX
A	0.80	-	1.22
A1	0.013	-	0.15
A2	0.75	0.90	1.07
b	0.30	-	0.51
b1	0.76	-	0.94
c	0.08	-	0.20
D	2.80	2.90	3.04
E	2.10	2.37	2.64
E1	1.20	1.30	1.40
e	1.92BSC		
e1	0.20BSC		
L	0.40	0.50	0.60
L1	(0.54)		
N	4		
θ	0°	-	8°

### Suggested Land Pattern



SYM	DIMENSIONS	
	MILLIMETERS	INCHES
C	2.20	0.087
E1	1.92	0.076
E2	1.72	0.068
G	0.80	0.031
X1	1.00	0.039
X2	1.20	0.047
Y	1.40	0.055
Z	3.60	0.141